

HIGH-STRENGTH COPPER ALLOY PLATE EXCELLENT IN OXIDE FILM ADHESIVENESS

ABSTRACT

The present invention is a Cu-Fe-P system copper alloy plate comprising Fe: 0.02–0.5% and P: 0.01–0.25% in mass % with the balance consisting of copper and unavoidable impurities and having the ratio Fe/P of Fe to P in mass % being 2.0 to 5.0, wherein: a ratio of the area of fine crystal grains less than 0.5 μm in equivalent circle diameter to an observation area when a surface is observed by EBSD analysis is 0.90 or less; and the ratio C1s/Cu2p of a peak area of C1s to a peak area of Cu2p on the surface by XPS analysis is 0.35 or less.

No Figure